The products are 15MBd high-speed opto-couplers in a plastic DIP8 package with different lead forming options. The device consists of a 850 nm AlGaAS LED, optically coupled to a very high speed integrated photo-detector logic gate with a strobable output. The output end of the product is a CMOS output, and the product has a strong common mode rejection capability. The coupled parameters are guaranteed over the temperature range of -40°C to +110°C. The products are widely used in communication interface, digital isolation for A/D, D/A conversion, high-voltage power systems, renewable energy inverters, medical imaging and patient monitoring.

High isolation 5000 VRMS
High speed – 15MBd typical
Operating temperature range -40°C to 110°C
REACH & RoHS compliance
HBM: H3A; MM: M4; CDM: C3
CQC approved
VDE approved
UL approved

LED	Output
ON	L
OFF	H

(Temperature=25°C)

Parameter		**Symbol**	**Value**	**Unit**
Input	Forward Current	I_F	50	mA
	Peak Forward Current	I_{FP}	1	A
	Reverse Voltage	V_R	6	V

	Input Power Dissipation	P_D	100	mW
Output	Supply Voltage	V_{CC}	7	V
	Output Voltage	V_O	V_{CC}+0.5	V
	Output Current	I_O	10	mA
	Output Power Dissipation	P_O	22	mW
Total Power Dissipation		P_{tot}	130	mW
solation Voltage		V_{iso}	5000	Vrms
Operating Temperature		T_{opr}	-40~110	
Junction Temperature		T_j	125	
Storage Temperature		T_{stg}	-55~125	
Soldering Temperature		T_{sol}	260	

: μ

:

(Temperature=25°C)

Parameter		Symbol	Condition	Min.	Typ.	Max.	Unit
	Forward Voltage	V_F	I_F=10mA	-	1.35	1.6	V
Input	Input Reverse Breakdown Voltage	BV					

	Propagation Delay Time to Logic Low	TPHL	I_F=7mA,C_L=15pF	-	70	100	ns

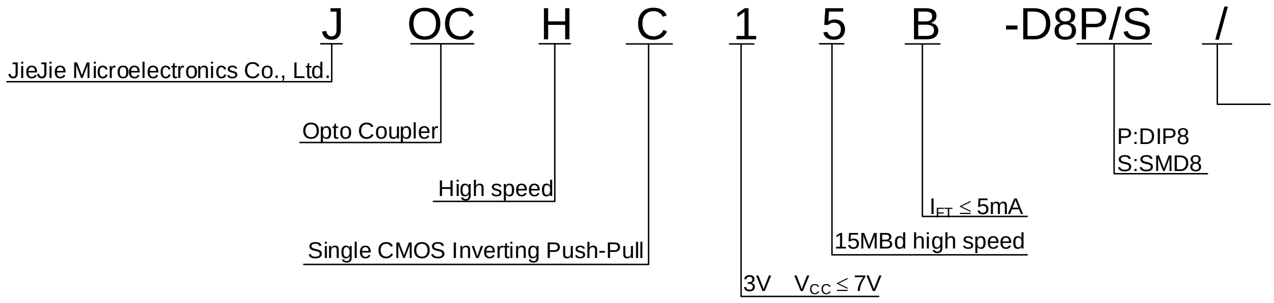

J OC H C 1 5 B -D8P/S /
JieJie Microelectronics Co., Ltd.
Opto Coupler
High speed
Single CMOS Inverting Push-Pull
3V V_{CC} ≤ 7V
15MBd high speed
I_{FT} ≤ 5mA
P:DIP8
S:SMD8

FIG.1: Forward Current vs. Forward Voltage

FIG.2: Max. Allowable LED Forward Current vs. Ambient Temperature

FIG.7: Propagation Delay vs. Ambient Temperature

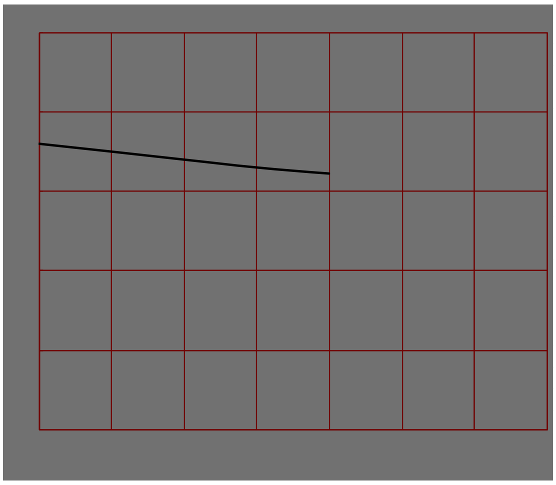
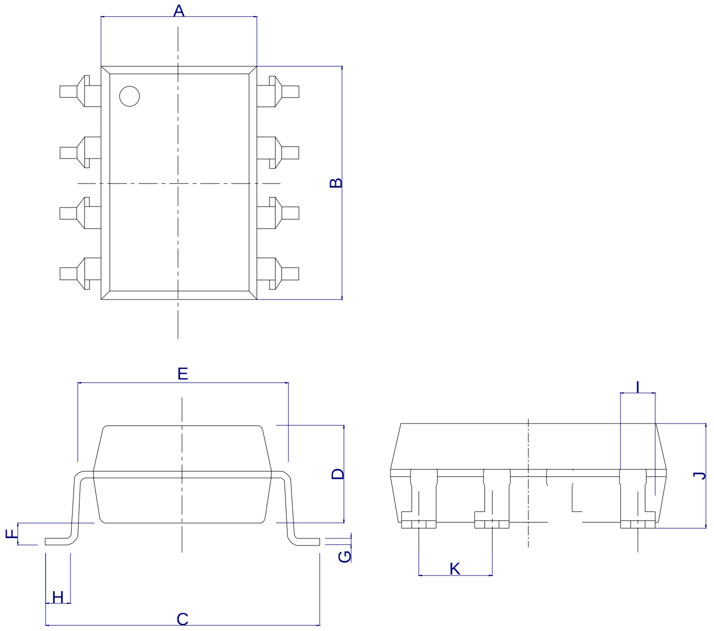


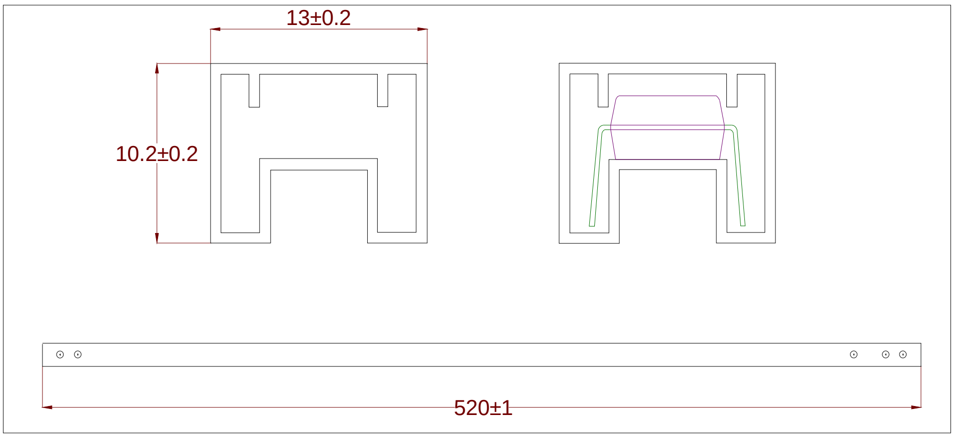
FIG.8: Propagation Delay vs. Ambient Temperature

Option SMD Type:

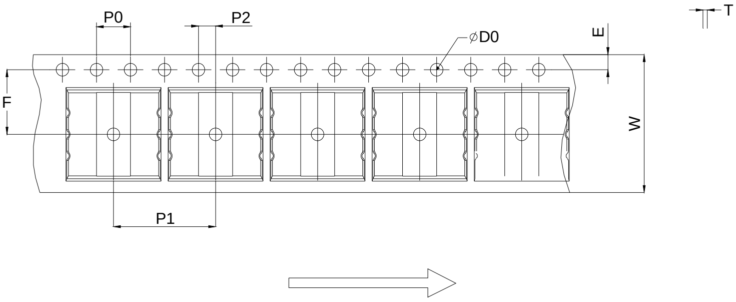


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.20		6.60	0.244		0.260
B	9.40		9.80	0.370		0.386
C	9.50		10.50	0.374		0.413
D	3.20		3.60	0.126		0.142
E	7.32		7.92	0.288		0.312
F	0.05		0.35	0.002		0.014
G	0.16		0.36	0.006		0.014
H	0.60		1.40	0.024		0.055
I	0.90		1.50	0.035		0.059
J	3.30		3.90	0.130		0.154
K	2.29		2.79	0.090		0.110

Standard DIP

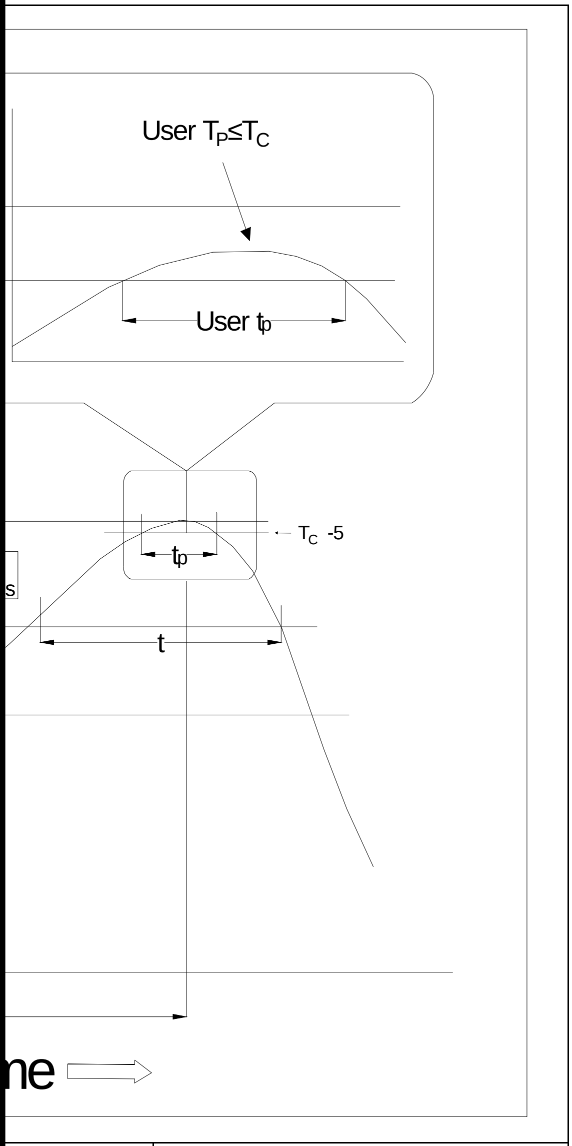


Option S/L

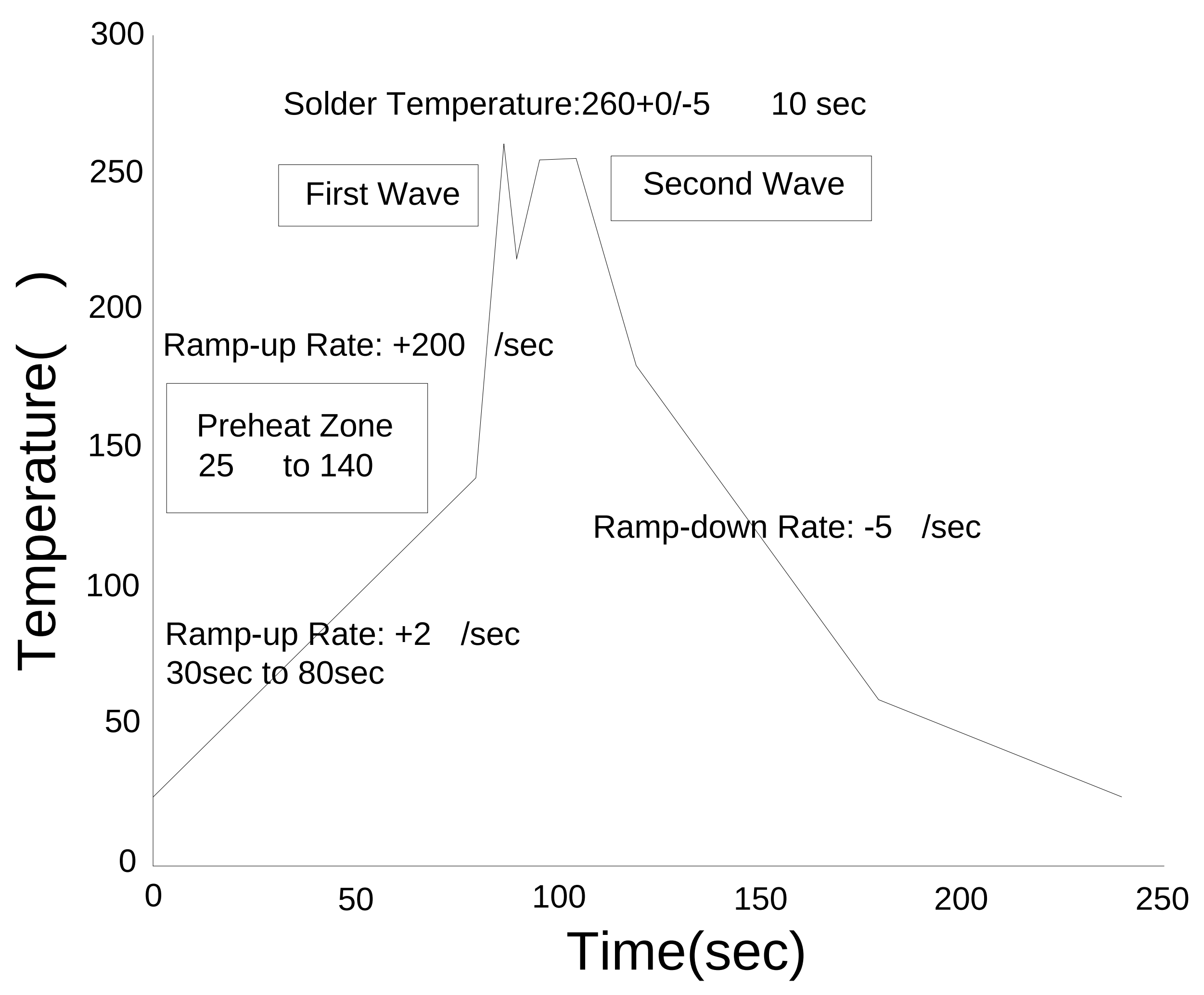


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	11.90	12.00	12.10	0.469	0.472	0.476
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
T	0.35	0.40	0.45	0.014	0.016	0.018
W	15.90	16.00	16.20	0.626	0.630	0.638

[redacted]



y Profile	Pb-Free Assembly Profile



Soldering Temperature	360 ± 5
Soldering Time	3s max.

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.

2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.

3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.

4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.

5. The component has a shelf life of one year when stored under standard conditions.

6. Recommend storage Temp.: 0~40°C;

   Recommend storage humidity: <60%;

   MSL level: MSL 1